

Product data sheet

## 1. General description

High voltage, high speed, planar passivated NPN power switching transistor in a SOT186A (TO220F) "full pack" plastic package.

## 2. Features and benefits

- Fast switching
- Isolated package
- Very high voltage capability
- Very low switching and conduction losses

## 3. Applications

- DC-to-DC converters
- High frequency electronic lighting ballasts
- Inverters
- Motor control systems

## 4. Quick reference data

#### Table 1. Quick reference data

Symbol	Parameter	Conditions	Min	Тур	Max	Unit
I <sub>CM</sub>	peak collector current	Fig. 1; Fig. 2; Fig. 3	-	-	10	А
P <sub>tot</sub>	total power dissipation	T <sub>h</sub> ≤ 25 °C; <u>Fig. 4</u>	-	-	32	W
V <sub>CESM</sub>	collector-emitter peak voltage	V <sub>BE</sub> = 0 V	-	-	1000	V
Static charac	teristics	·				,
h <sub>FE</sub>	DC current gain	$I_{C}$ = 5 mA; $V_{CE}$ = 5 V; $T_{h}$ = 25 °C; Fig. 11	10	22	35	
		I <sub>C</sub> = 500 mA; V <sub>CE</sub> = 5 V; T <sub>h</sub> = 25 °C; Fig. 11	14	25	35	

## 5. Pinning information

Table 2. F	Pinning inf	formation		
Pin	Symbol	Description	Simplified outline	Graphic symbol
1	В	base	mb	С
2	С	collector		в
3	Е	emitter		
mb	n.c.	mounting base; isolated	TO-220F (SOT186A)	Ë sym123

# 6. Ordering information

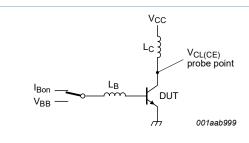
Table 3. Ordering information						
Type number	Package					
	Name	Description	Version			
BUJ303AX	TO-220F	plastic single-ended package; isolated heatsink mounted; 1 mounting hole; 3-lead TO-220 "full pack"	SOT186A			

## 7. Limiting values

### Table 4. Limiting values

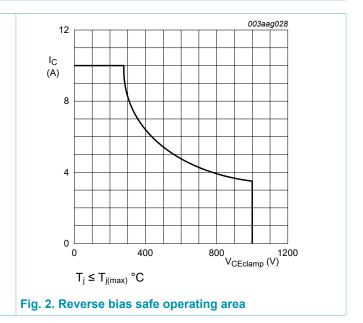
In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions	Min	Мах	Unit
V <sub>CESM</sub>	collector-emitter peak voltage	V <sub>BE</sub> = 0 V	-	1000	V
V <sub>CEO</sub>	collector-emitter voltage	I <sub>B</sub> = 0 A	-	500	V
I <sub>C</sub>	collector current	Fig. 1; Fig. 2; Fig. 3	-	5	А
I <sub>CM</sub>	peak collector current		-	10	А
I <sub>B</sub>	base current	DC	-	2	А
I <sub>BM</sub>	peak base current		-	4	А
P <sub>tot</sub>	total power dissipation	T <sub>h</sub> ≤ 25 °C; <u>Fig. 4</u>	-	32	W
T <sub>stg</sub>	storage temperature		-65	150	°C
Tj	junction temperature		-	150	°C

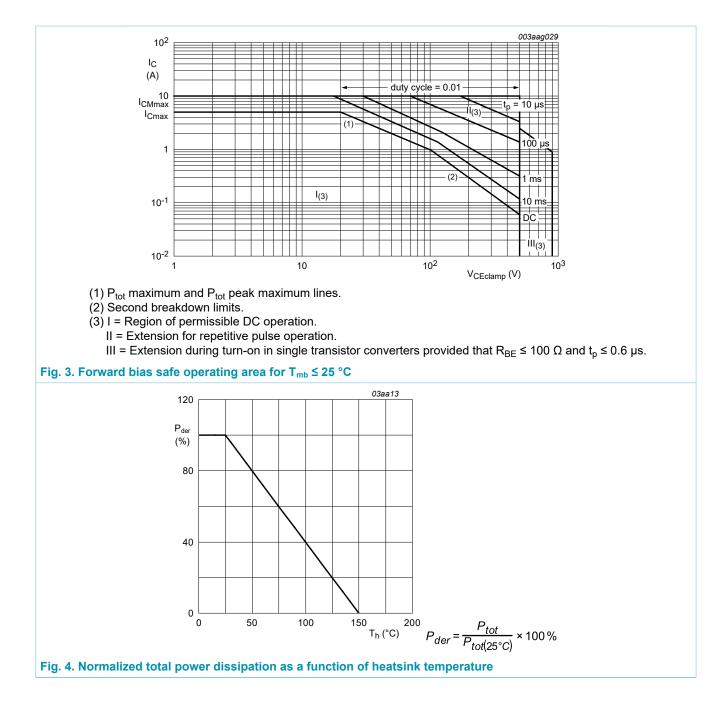


 $\begin{array}{l} V_{CL(CE)} \leq 1000 \; V; \; V_{CC} = 150 \; V; \; V_{BB} = - \; 5 \; V; \\ L_B = 1 \; \mu H; \; L_C = 200 \; \mu H \end{array}$ 

Fig. 1. Test circuit for reverse bias safe operating area

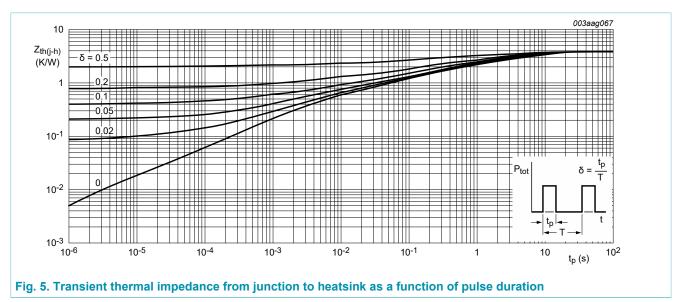


#### **NPN** power transistor



## 8. Thermal characteristics

Symbol	Parameter	Conditions	Min	Тур	Max	Unit
R <sub>th(j-h)</sub>	thermal resistance from junction to heatsink	with heatsink compound; Fig. 5	-	-	3.95	K/W
R <sub>th(j-a)</sub>	thermal resistance from junction to ambient free air	in free air	-	55	-	K/W



## 9. Isolation characteristics

Table 6. Isolat	ion characteristics		 			
Symbol	Parameter	Conditions	Min	Тур	Max	Unit
V <sub>isol(RMS)</sub>	RMS isolation voltage	50 Hz $\leq$ f $\leq$ 60 Hz; RH $\leq$ 65 %; T <sub>h</sub> = 25 °C; from all terminals to external heatsink; clean and dust free	-	-	2500	V
C <sub>isol</sub>	isolation capacitance	from collector to external heatsink; f = 1 MHz; $T_h$ = 25 °C	-	10	-	pF

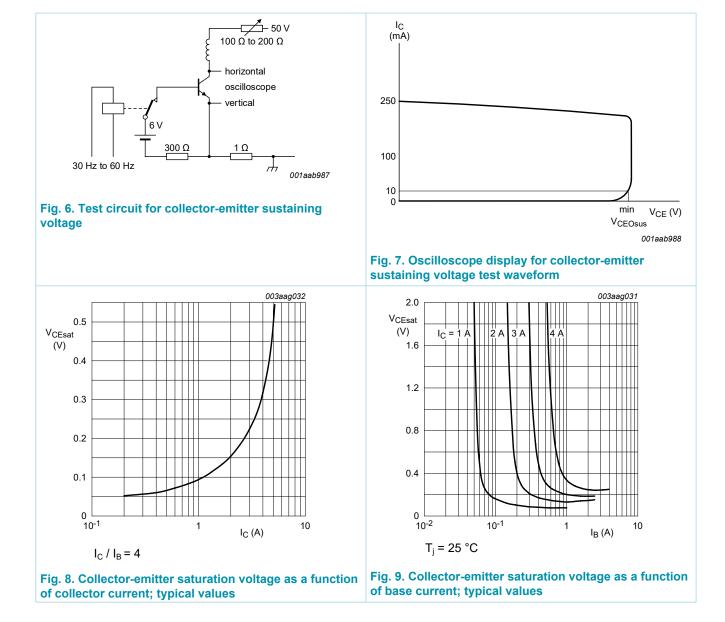
## **10. Characteristics**

Symbol	Parameter	Conditions	Min	Тур	Max	Unit
Static chara	acteristics	·				
I <sub>CES</sub>	collector-emitter cut-off	$V_{BE}$ = 0 V; $V_{CE}$ = 1000 V; Measured	-	-	1	mA
	current (base shorted)	with half-sine wave voltage (curve tracer)	-	-	2	mA
I <sub>CBO</sub>	collector-base cut-off current (emitter open)	$V_{CB}$ = 1000 V; I <sub>E</sub> = 0 A; T <sub>h</sub> = 25 °C; Measured with half-sine wave voltage (curve tracer)	-	-	1	mA
I <sub>CEO</sub>	collector-emitter cut-off current (base open)	$V_{CE}$ = 500 V; $I_B$ = 0 A; $T_h$ = 25 °C; Measured with half-sine wave voltage (curve tracer)	-	-	0.1	mA
I <sub>EBO</sub>	emitter-base cut-off current (collector open)	V <sub>EB</sub> = 9 V; I <sub>C</sub> = 0 A; T <sub>h</sub> = 25 °C	-	-	0.1	mA
V <sub>CEOsus</sub>	collector-emitter sustaining voltage (base open)	I <sub>B</sub> = 0 A; I <sub>C</sub> = 100 mA; L <sub>C</sub> = 25 mH; T <sub>h</sub> = 25 °C; <u>Fig. 6</u> ; <u>Fig. 7</u>	500	-	-	V
V <sub>CEsat</sub>	collector-emitter saturation voltage	I <sub>C</sub> = 3 A; I <sub>B</sub> = 0.6 A; T <sub>h</sub> = 25 °C; <u>Fig. 8;</u> <u>Fig. 9</u>	-	0.35	1.5	V
V <sub>BEsat</sub>	base-emitter saturation voltage	I <sub>C</sub> = 3 A; I <sub>B</sub> = 0.6 A; T <sub>h</sub> = 25 °C; <u>Fig. 10</u>	-	1.01	1.3	V
h <sub>FE</sub>	DC current gain	$I_{C}$ = 5 mA; $V_{CE}$ = 5 V; $T_{h}$ = 25 °C; Fig. 11	10	22	35	
		I <sub>C</sub> = 500 mA; V <sub>CE</sub> = 5 V; T <sub>h</sub> = 25 °C; <u>Fig. 11</u>	14	25	35	
h <sub>FEsat</sub>	DC saturation current gain	I <sub>C</sub> = 2.5 A; V <sub>CE</sub> = 5 V; T <sub>h</sub> = 25 °C; <u>Fig. 11</u>	10	13.5	17	
		I <sub>C</sub> = 3 A; V <sub>CE</sub> = 5 V; T <sub>h</sub> = 25 °C; <u>Fig. 11</u>	-	11	-	
Dynamic ch	naracteristics (switching tir	nes - resistive load)				
t <sub>s</sub>	turn-off delay time	I <sub>C</sub> = 2.5 A; I <sub>Bon</sub> = 0.5 A; I <sub>Boff</sub> = -0.5 A;	-	3.3	4	μs
t <sub>f</sub>	fall time	$R_L$ = 75 Ω; $T_h$ = 25 °C; <u>Fig. 12</u> ; <u>Fig. 13</u>	-	0.33	0.45	μs
Dynamic ch	naracteristics (switching tir	nes - inductive load)				
t <sub>s</sub>	turn-off delay time	$    I_C = 2.5 \text{ A}; \    I_{Bon} = 0.5 \text{ A}; \   V_{BB} = -5 \text{ V}; \\     L_B = 1 \  \mu \text{H}; \   T_h = 25 \   ^\circ\text{C}; \   \underline{\text{Fig. 14}}; \   \underline{\text{Fig. 15}} $	-	1.4	1.6	μs
		$    I_C = 2.5 \text{ A}; \    I_{Bon} = 0.5 \text{ A}; \   V_{BB} = -5 \text{ V}; \\     L_B = 1 \  \mu \text{H}; \   T_h = 100 \   ^\circ \text{C}; \   \underline{\text{Fig. 14}}; \   \underline{\text{Fig. 15}} $	-	1.7	1.9	μs
t <sub>r</sub>	rise time	$    I_C = 2.5 \text{ A}; \    I_{Bon} = 0.5 \text{ A}; \  V_{BB} = -5 \text{ V}; \\     L_B = 1 \  \mu \text{H}; \  T_h = 25 \  ^\circ\text{C}; \  \overline{\text{Fig. 14}}; \  \overline{\text{Fig. 15}} $	-	145	160	ns
		$I_{C}$ = 2.5 A; $I_{Bon}$ = 0.5 A; $V_{BB}$ = -5 V; $L_{B}$ = 1 µH; $T_{h}$ = 100 °C; <u>Fig. 14</u> ; <u>Fig. 15</u>	-	160	200	ns

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#### **NPN** power transistor



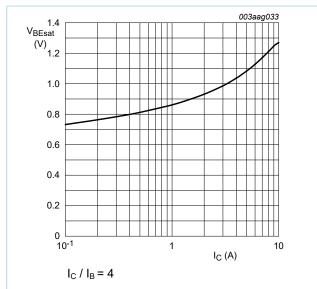
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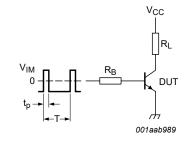
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#### **NPN** power transistor

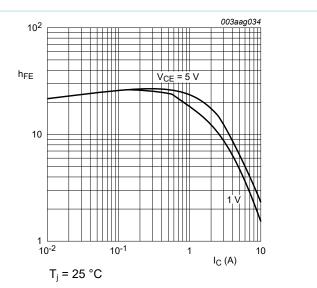




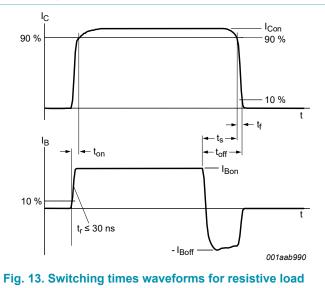


$$\label{eq:VIM} \begin{split} V_{IM} &= -6 \text{ to } + 8 \text{ V}; \ V_{CC} = 250 \text{ V}; \ t_p = 20 \text{ us}; \ \delta = t_p/T = 0.01 \\ R_B \text{ and } R_L \text{ calculated from } I_{Con} \text{ and } I_{Bon} \text{ requirements}. \end{split}$$

Fig. 12. Test circuit for resistive load switching



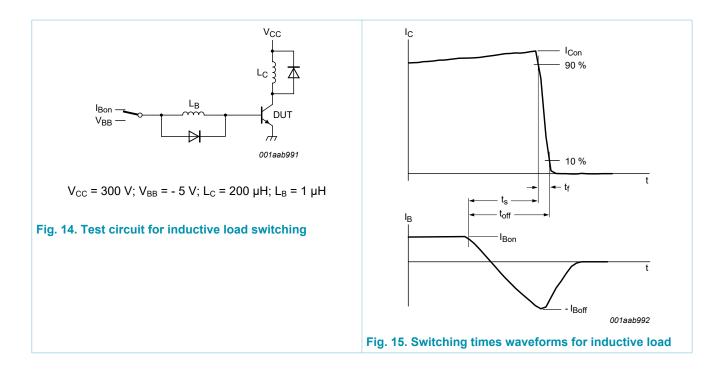




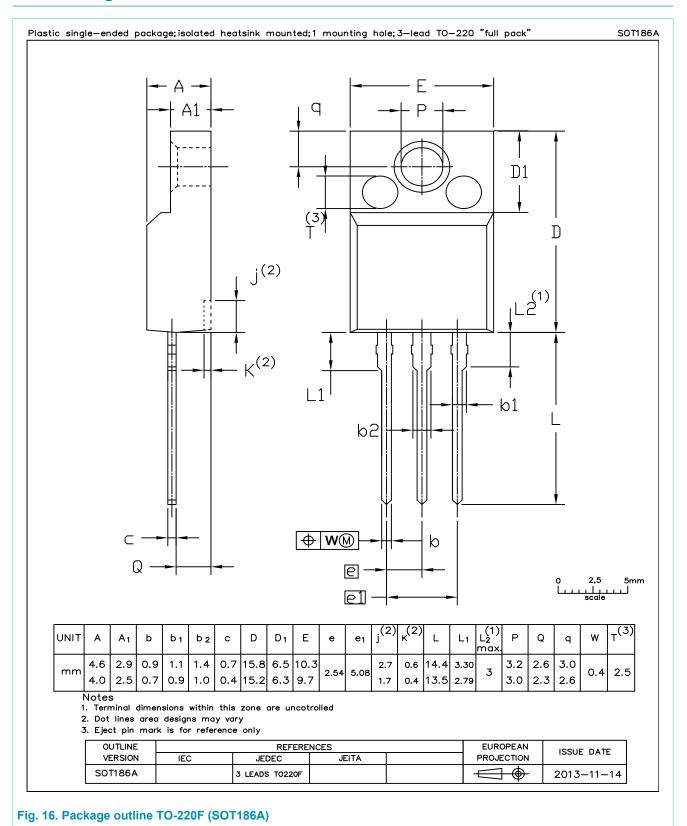
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## 11. Package outline



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## 12. Legal information

#### **Data sheet status**

Document status [1][2]	Product status [ <u>3]</u>	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

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